

# L-726

## Woven Prepreg, Aramid Phenolic



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### Product Data Sheet

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#### Description

L-726 is a 275°F (135°C) curing phenolic prepreg with excellent fire, smoke, and toxicity properties. L-726 is available on 281 style aramid fabric or other styles of fabric as requested. L-726 is intended to be used as a single ply or multiple ply skin for aramid/phenolic honeycomb or aluminum honeycomb sandwich panels.

#### Advantages of L-726

- ❖ When used with L-310 phenolic adhesive film, L-726 prepreg facings create sandwich panels with high peel strength and high toughness.
- ❖ Processing of L-726 can be easily adapted to most heated presses or autoclaves.
- ❖ L-726 is also an excellent laminating prepreg when heat resistance is a requirement.
- ❖ Structure requiring ultra light weight and durability are candidates for the L-726 product.

#### Physical Properties on 281 Style Aramid Fabric

- *Standard Weight:* 0.070 lbs/ft<sup>2</sup> (342 g/m<sup>2</sup>)
- *Standard Resin Content:* 50% by weight
- *Volatile Content:* 2-6%
- *Standard Tack:* Low tack
- *Cured Ply Thickness:* 0.009" (0.23 mm)
- *Other Weights, Resin Contents, and Fabrics are Available.*

#### Availability

- *Up to 60" width in rolls up to 100 yards long (152 cm x 91 m)*

#### Shelf Life

- *6 months at 40°F (4°C) or below*
- *14 days at room temperature (70°F or 21°C)*

#### Cure Cycles

- *60 minutes at 275°F (135°C), or*
- *120 minutes at 260°F (127°C).*

#### Flammability

- *Self Extinguishing per FAR part 25.853*



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## Sandwich Properties\*

Core: ¼" cell x 0.004" (6.35 mm cell x 0.10 mm) Aluminum Foil

Adhesive: 1 ply L-310 each side

Facings: 2 plies L-726-281 each side

- *RT Flatwise Tensile Strength:* 890 PSI (6.1 MPa)
- *RT Sandwich Peel Strength:* 9 in lb/in (40 Nm/m)

\*Sandwich peel strength varies with the orientation of fibers directly against the core and test direction.

- ❖ Fibers laid up parallel with the test direction produce minimum strengths.
- ❖ Fibers laid up perpendicular to the test direction produce maximum strengths.
- ❖ L-726-281 sandwich peel strength ranges from 7-13 in lb/in (31-58 Nm/m).

## Mechanical Data

PROPERTY	LAMINATE PROPERTIES	
	25 PSI CURE	TEST METHOD
<b>ULTIMATE TENSILE STRENGTH</b>		
Room Temperature (RT)	56 KSI (386 MPa)	ASTM D638
160°F (71°C)	49 KSI (338 MPa)	ASTM D638
500°F (260°C) after 30 min soak at 500°F	43 KSI (296 MPa)	ASTM D638
<b>TENSILE MODULUS</b>		
Room Temperature (RT)	3.3 MSI (23 GPa)	ASTM D638
160°F (71°C)	3.3 MSI (23 GPa)	ASTM D638
RT(WET)	3.2 MSI (22 GPa)	ASTM D638
<b>ULTIMATE COMPRESSION STRENGTH</b>		
Room Temperature (RT)	21 KSI (145 MPa)	ASTM D695
160°F (71°C)	20 KSI (138 MPa)	ASTM D695
500°F (260°C) after 30 min soak at 500°F	19 KSI (130 MPa)	ASTM D695
<b>COMPRESSION MODULUS</b>		
Room Temperature (RT)	3.0 MSI (21 GPa)	ASTM D695
160°F (71°C)	3.0 MSI (21 GPa)	ASTM D695
RT(WET)	2.9 MSI (20 GPa)	ASTM D695
<b>ULTIMATE FLEXURAL STRENGTH</b>		
Room Temperature (RT)	54 KSI (372 MPa)	ASTM D790
<b>FLEXURAL MODULUS</b>		
Room Temperature (RT)	3.1 MSI (21 GPa)	ASTM D790
160°F (71°C)	-	ASTM D790

### NOTICE:

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